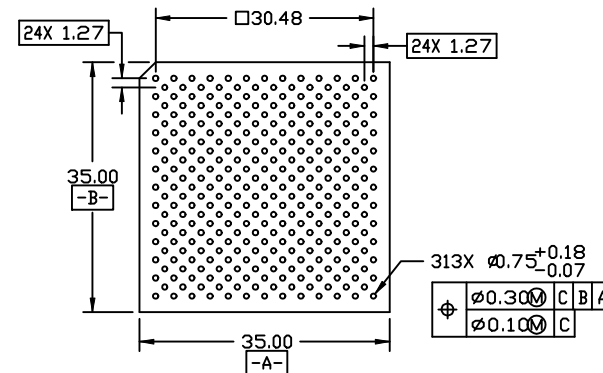
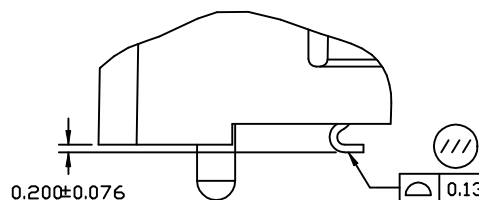
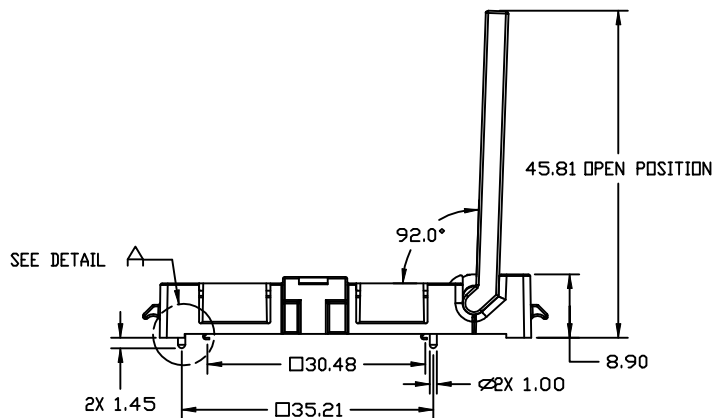


RECOMMENDED PCB PAD PATTERN



-C- IS ESTABLISHED THROUGH THE PLANE TANGENT TO THE BALL LOWER SURFACES

BGA PACKAGE DIMENSION SPECIFICATIONS



DETAIL A  
SCALE 8:1

- MATERIAL:  
 1) ALL PLASTIC COMPONENTS - PPS/PEI OR EQUIV.  
 2) CAM - ZINC-ALUMINUM  
 3) CONTACTS - BeCu, SnPb OVER Ni PLATING

DIMENSIONS ARE IN MILLIMETERS INTERPRET PER ANSI Y14.5M-1982	Vendor: CTI Tech. 602-581-5330 Phoenix, AZ	Vendor: CTI Tech. DWG NO. or PART #: 8635-313-0-00	Actel Corp Sunnyvale, CA	Z-LOK BGA SURFACE MOUNT SOCKET 35MM, 313LD, 1.27 C/C		
THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION WHICH IS THE CONFIDENTIAL PROPERTY OF: Actel Corp. Sunnyvale CA		ENGR Ray Kuang 2/9/98 APPD	PROJECTION 	SIZE	SPEC 1-07-09023	REV 0
			Actel Part #: SC-BGA313	SHEET 1 of 1		